PART INFORMATION

Mfg Item Number	MPXHZ6250AC6T1
Mfg Item Name	SNSR SSOP 08 PORTED

SUPPLIER

Company Name	Freescale Semiconductor Inc
Company Unique ID	14-141-7928
Response Date	2014-11-04
Response Document ID	0887K50010S285A1.32
Contact Name	Freescale Semiconductor Inc
Contact Title	Product Technical Support
Contact Phone	1-800-521-6274
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Authorized Representative	Daniel Binyon
Representative Title	EPP Customer Response
Representative Phone	512-895-3406
Representative Email	eppanlst@freescale.com
URL for Additional Information	www.freescale.com

DECLARATION

EU RoHS	Yes
Pb Free	No
HalogenFree	No
Plating Indicator	e4
EU RoHS Exemption(s)	7c-I

MANUFACTURING

Mfg Item Number	MPXHZ6250AC6T1
Mfg Item Name	SNSR SSOP 08 PORTED
Version	ALL
Weight	0.521500
UoM	g
Unit Volume	EACH
J-STD-020 MSL Rating	
Peak Processing Temperature	250 C
Max Time at Peak Temperature	30 seconds
Number of Processing Cycles	3

RoHS	
RoHS Directive	2011/65/EU
RoHS Definition	RoHS Definition: Quantity limit of 0.1% by mass (1000 PPM) of homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material of Cadmium
RoHS Legal Definition	Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part(s) identified on this form contains lead, mercury, cadmium, hexavalent chromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a RoHS restricted substance) in excess of the applicable quantity limit identified below. If a homogeneous material within the part(s) contains a RoHS restricted substance in excess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s),the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Suppliers liability and the Companys remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Suppliers Standard Terms and Conditions of Sale applicable to such part(s) shall apply.
RoHS Declaration	4 - Item(s) does not contain RoHS restricted substances per the definition above except for selected exemptions
Supplier Acceptance	Accepted
Signature	Daniel Binyon
Exemption List Version	2012/51/EU
Exemptions in this part	7c-I:Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound
List of Freescale Accepted Exemptions	6(a) : Lead as an alloying element in steel for machining purposes and in galvanized steel containing up to 0.35% lead by weight 6(b) : Lead as an alloying element in aluminium containing up to 0.4% lead by weight 6(c) : Copper alloy containing up to 4% lead by weight 7(a) : Lead in high melting temperature type solders (i.e. lead-based alloys containing 85% by weight or more lead) 7(b) : Lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signaling, transmission, and network management for telecommunications 7(c)-I : Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound 7(c)-II : Lead in dielectric ceramic in capacitors for a rated voltage of 125 V AC or 250 V DC or higher 7(c)-III : Lead in dielectric ceramic in capacitors for a rated voltage of less than 125 V AC or 250 V DC 7(c)-IV : Lead in PZT based dielectric ceramic materials for capacitors being part of integrated circuits or discrete semiconductors 15 : Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit flip chip packages

MATERIAL COMPOSITION

Homogeneous Material	Weight	SubstanceClass	Substance	CAS	Exemption	SubstanceWeight	UoM	SubPart PPM	SubPart%		ARTICLEPPM	ARTICLE%
Cap/Cover	0.0809						g					
Cap/Cover		Metals	Chromium, metal	7440-47-3		0.01457947	g	180216	18.0216		27956	2.7956
Cap/Cover		Solvents, additives, and other materials	Sulfur	7704-34-9		0.00002427	g	300	0.03		46	0.0046
Cap/Cover		Solvents, additives, and other materials	Phosphorus	7723-14-0		0.00003236	g	400	0.04		62	0.0062
Cap/Cover		Solvents, additives, and other materials	Silicon	7440-21-3		0.00060748	g	7509	0.7509		1164	0.1164
Cap/Cover		Metals	Iron, metal	7439-89-6		0.06484645	g	801563	80.1563		124346	12.4346
Cap/Cover		Metals	Manganese, metal	7439-96-5		0.00080997	g	10012	1.0012		1553	0.1553
Non-Conductive Epoxy/Adhesive	0.0006						g					
Non-Conductive Epoxy/Adhesive		Solvents, additives, and other materials	Silicone gum	67762-94-1		0.00000619	g	10324	1.0324		11	0.0011
Non-Conductive Epoxy/Adhesive		Solvents, additives, and other materials	Siloxanes and Silicones, di-Me, Me vinyl, vinyl group-terminated	68083-18-1		0.00007375	g	122911	12.2911		141	0.0141
Non-Conductive Epoxy/Adhesive		Solvents, additives, and other materials	Siloxanes and silicones, di-Me, vinyl group-terminated	68083-19-2		0.00023599	g	393313	39.3313		452	0.0452
Non-Conductive Epoxy/Adhesive		Solvents, additives, and other materials	Proprietary Material-Other siloxanes and silicones	-		0.00013274	g	221239	22.1239		254	0.0254
Non-Conductive Epoxy/Adhesive		Glass	D4 and HMDZ treated Silicon Dioxide	68937-51-9		0.0000885	g	147493	14.7493		169	0.0169
Non-Conductive Epoxy/Adhesive		Glass	Silica, crystalline - quartz (SiO2)	14808-60-7		0.00005605	g	93412	9.3412		107	0.0107
Non-Conductive Epoxy/Adhesive		Metals	Titanium (IV) Oxide	13463-67-7		0.00000678	g	11308	1.1308		13	0.0013
Port	0.1305						g					
Port		Plastics/polymers	Polyphenylene Sulfide (PPS)	26125-40-6		0.07777278	g	595960	59.596		149132	14.9132
Port		Glass	Proprietary Material-Other glass compounds (without lead, chromium, cadmium or mercury)	-		0.05272722	g	404040	40.404		101106	10.1106
Copper Lead Frame	0.2529						g					
Copper Lead Frame		Metals	Copper, metal	7440-50-8		0.21364688	g	844788	84.4788		409697	40.9697
Copper Lead Frame		Metals	Gold, metal	7440-57-5		0.00016894	g	668	0.0668		323	0.0323
Copper Lead Frame		Solvents, additives, and other materials	Phosphorus	7723-14-0		0.00032599	g	1289	0.1289		625	0.0625
Copper Lead Frame		Metals	Iron, metal	7439-89-6		0.00487515	g	19277	1.9277		9348	0.9348
Copper Lead Frame		Nickel (external applications only)	Nickel	7440-02-0		0.00237094	g	9375	0.9375		4546	0.4546
Copper Lead Frame		Metals	Palladium, metal	7440-05-3		0.00011608	g	459	0.0459		222	0.0222
Copper Lead Frame		Plastics/polymers	Polyphenylene Sulfide (PPS)	26125-40-6		0.00977737	g	38661	3.8661		18748	1.8748
Copper Lead Frame		Glass	Fibrous-glass-wool	65997-17-3		0.02118417	g	83765	8.3765		40621	4.0621
Copper Lead Frame		Metals	Zinc, metal	7440-66-6		0.00043448	g	1718	0.1718		833	0.0833
Bonding Agent	0.0163						g					
Bonding Agent		Metals	Proprietary Material-Other aluminum compounds	-		0.007335	g	450000	45		14065	1.4065
Bonding Agent		Solvents, additives, and other materials	Other guanidine compounds	-		0.0004075	g	25000	2.5		781	0.0781
Bonding Agent		Solvents, additives, and other materials	Carbon Black	1333-86-4		0.0004075	g	25000	2.5		781	0.0781
Bonding Agent		Plastics/polymers	Other phenolic resins	-		0.00815	g	500000	50		15627	1.5627
Pb Glass Frit Semiconductor Di	0.0131				7c-I		g					
Pb Glass Frit Semiconductor Di		Lead/Lead Compounds	Lead (II) titanate	12060-00-3		0.00013599	g	10381	1.0381		260	0.026
Pb Glass Frit Semiconductor Di		Glass	Fibrous-glass-wool	65997-17-3		0.00013025	g	9943	0.9943		249	0.0249
Pb Glass Frit Semiconductor Di		Solvents, additives, and other materials	2,2,4-trimethyl-1,3-pentanediol-1-monoisobutyrate	25265-77-4		0.00013025	g	9943	0.9943		249	0.0249
Pb Glass Frit Semiconductor Di		Glass	Silicon, doped	-		0.01270351	g	969733	96.9733		24359	2.4359
Gel Die Encapsulant	0.0133						g					
Gel Die Encapsulant		Solvents, additives, and other materials	Fluorosilicone monomer (fluorosilicone rubber)	2374-14-3		0.010374	g	780000	78		19892	1.9892
Gel Die Encapsulant		Plastics/polymers	Oxetane, 2,2,3,3-tetrafluoro-homopolymer, fluorinated	113114-19-5		0.002926	g	220000	22		5610	0.561
Gel Die Encapsulant	0.0133						g					
Gel Die Encapsulant		Solvents, additives, and other materials	Fluorosilicone monomer (fluorosilicone rubber)	2374-14-3		0.010374	g	780000	78		19892	1.9892
Gel Die Encapsulant		Plastics/polymers	Oxetane, 2,2,3,3-tetrafluoro-homopolymer, fluorinated	113114-19-5		0.002926	g	220000	22		5610	0.561
Bonding Wire	0.0006						g					
Bonding Wire		Metals	Gold, metal	7440-57-5		0.0006	g	1000000	100		1150	0.115

LINKS	
MCD LINK	
Freescale website	http://www.freescale.com
GENERAL ENVIRONMENTAL COMPLIANCE LINKS	
RoHS signed letter	http://www.freescale.com/files/abstract/corporate/ehs_epp/ENV_ROHS_Freescale_Response.pdf
China RoHS	http://www.freescale.com/chinarohs
REACH signed letter	http://www.freescale.com/files/abstract/corporate/ehs_epp/ENV_REACH_Freescale_Response.pdf
ELV signed letter	http://www.freescale.com/files/abstract/corporate/ehs_epp/ENV_ELV_Freescale_Reponse.pdf
Conflict Minerals statement	http://www.freescale.com/files/abstract/corporate/ehs_epp/ENV_CONFLICT_METAL_Freescale_Response.pdf
FREESCALE ENVIRONMENTAL INFORMATION	
EPP website	http://www.freescale.com/epp
FAQ	http://www.freescale.com/webapp/sps/site/overview.jsp?code=ENVIRON_FAQ
Technical Service Request	https://www.freescale.com/webapp/servicerequest.create_SR.framework?defaultCategory=Hardware Product Support&defaultTopic=Environmentally Preferred Prod
LINKS TO BLANK IPC1752 FORMS	
Blank IPC1752 v1.1 Form	http://www.freescale.com/files/abstract/corporate/ehs_epp/IPC-1752-2_v1.1_MCD_Template.pdf

IPC1752 XML LINKS

http://www.freescale.com/mcds/MPXHZ6250AC6T1_IPC1752_v11.xml

http://www.freescale.com/mcds/MPXHZ6250AC6T1_IPC1752A.xml